

■ Pin

Pin No.	Pin Name	Pin No.	Pin Name
1	Head SW Changeover	12	Ch. I, II Side Envelope Detection
2	Initial Stage Bias(Ch. I)	13	Ch. III, IV Side Envelope Detection
3	Initial Stage Input(Ch. I)	14	Envelope Comparative Output
4	Initial Stage Input(Ch. II)	15	Chroma Output
5	Initial Stage Bias(Ch. II)	16	V _{CC}
6	Input Stage GND	17	Envelope Comparative Circuit Stop SW
7	Initial Stage Bias(Ch. III)	18	Peaking Circuit Peak Constant
8	Initial Stage Input(Ch. III)	19	Output Stage GND
9	Initial Stage Input(Ch. IV)	20	AGC Output
10	Initial Stage Bias(Ch. IV)	21	AGC Reverse Phase Output
11	Head Amp. SW Changeover	22	AGC Control Signal Detection

■ Absolute Maximum Ratings (T_a=25°C)

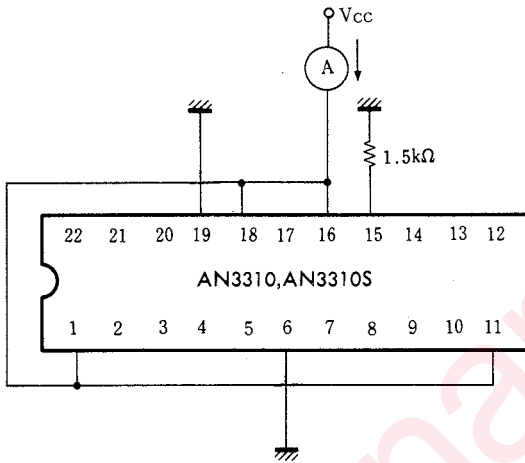
Item	Symbol	Rating	Unit
Supply Voltage	V _C	6.0	V
Power Dissipation(T _a =70°C)	P _D	250	mW
Operating Ambient Temperature	T _{opr}	-20~+70	°C
Storage Temperature	T _{stg}	-55~+150	°C

■ Electrical Characteristics (T_a=25°C)

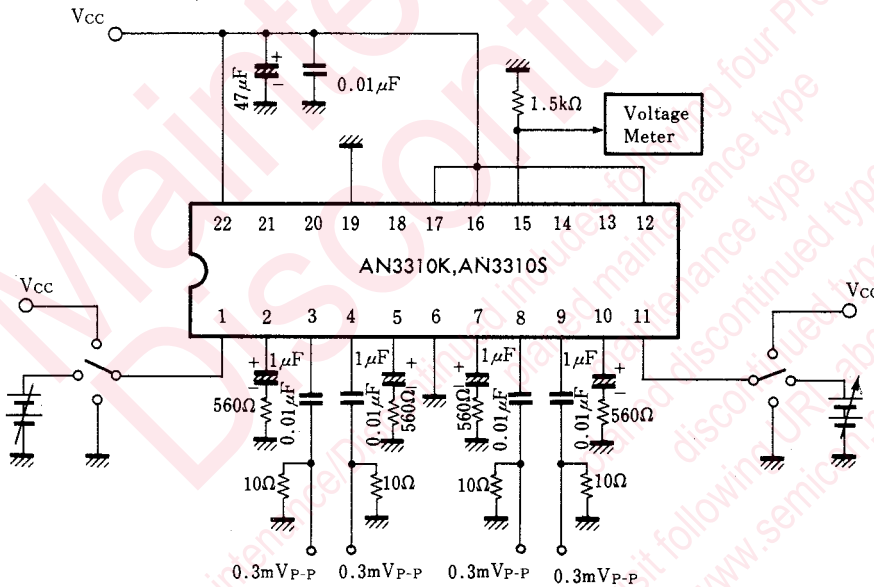
Item	Symbol	Test Circuit	Condition	min.	typ.	max.	Unit
Circuit Current	I ₁₆	1	V _{CC} =5V	16		40	mA
Ch. I Gain	G ₃₋₁₅	2	V _{CC} =5V, f=1MHz	50.5		60.5	dB
Ch. II Gain	G ₄₋₁₅	2	V _{CC} =5V, f=1MHz	50.5		60.5	dB
Ch. III Gain	G ₈₋₁₅	2	V _{CC} =5V, f=1MHz	50.5		60.5	dB
Ch. IV Gain	G ₉₋₁₅	2	V _{CC} =5V, f=1MHz	50.5		60.5	dB
AGC Output Amplitude	v ₂₀	3	V _{CC} =5V, f=4MHz	100		190	mV _{P-P}
AGC Control Sensitivity	v ₂₀	3	V _{CC} =5V, f=4MHz			3	dB
H.SW Changeover Sensitivity	S ₁	2	V _{CC} =5V			1	V
H.A.SW Changeover Sensitivity	S ₁₁	2	V _{CC} =5V			1	V
Noise voltage Referred to Input(I)	V _{ni3-15}	4	V _{CC} =5V, 1MHz BPF			1	μV _{rms}
Noise voltage Referred to Input(II)	V _{ni4-15}	4	V _{CC} =5V, 1MHz BPF			1	μV _{rms}
Noise voltage Referred to Input(III)	V _{ni8-15}	4	V _{CC} =5V, 1MHz BPF			1	μV _{rms}
Noise voltage Referred to Input(IV)	V _{ni9-15}	4	V _{CC} =5V, 1MHz BPF			1	μV _{rms}
Envelope Comparative Output Amplitude	v ₁₄	5	V _{CC} =5V	4.3			V _{P-P}
Envelope Comparative Output Stop Sensitivity	S ₁₇	5	V _{CC} =5V			1.2	V

Note : Operating Supply Voltage Range : V_{CC(oper)}=4.5~5.5V

Test Circuit 1 (I₁₆)



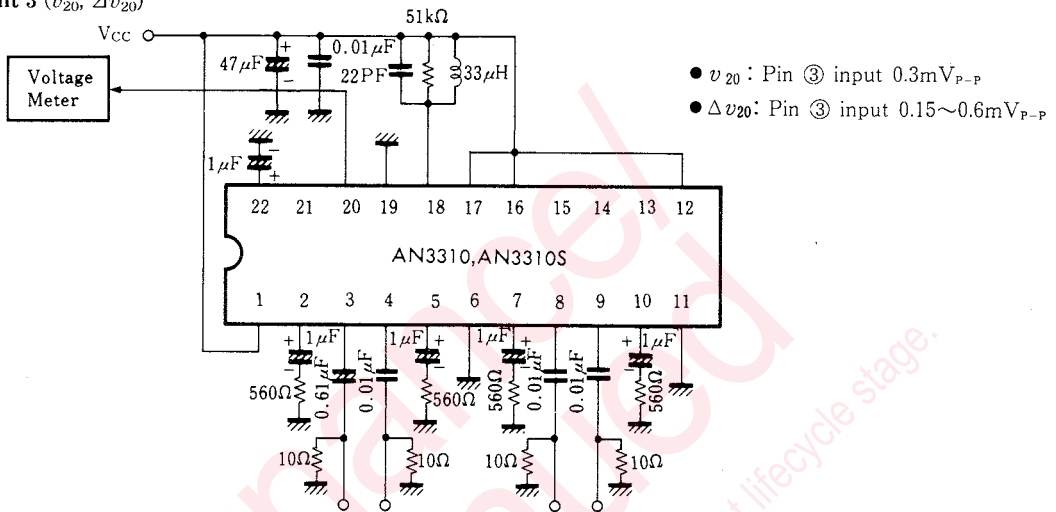
Test Circuit 2 (G₃₋₁₅, G₄₋₁₅, G₈₋₁₅, G₉₋₁₅, S₁, S₁₁)



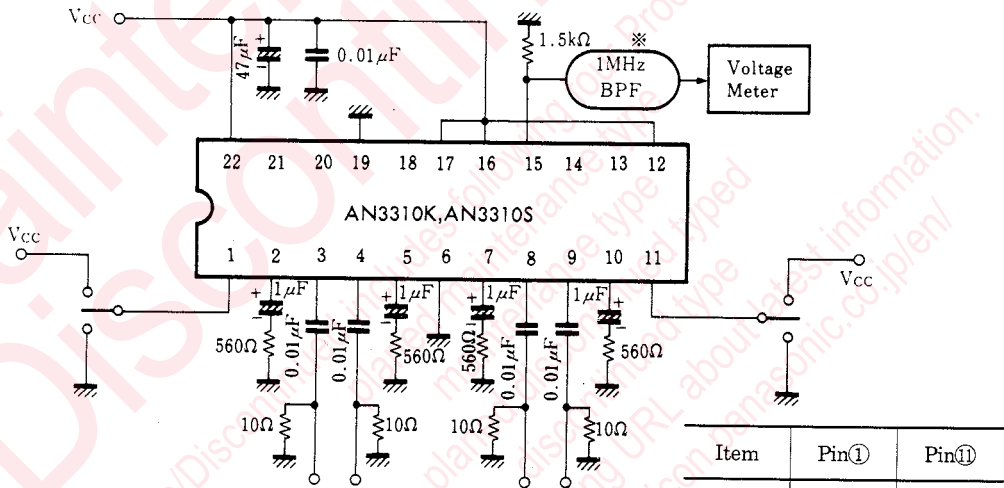
Item	①Pin	⑩Pin	Input Pin
G ₃₋₁₅	V _{CC}	GND	③
G ₄₋₁₅	GND	GND	④
G ₈₋₁₅	V _{CC}	V _{CC}	⑧
G ₉₋₁₅	GND	V _{CC}	⑨

- S₁, S₁₁ : Pin ④ 0.3mV_{P-P} input (f_{in}=1MHz)
- S₁ : Decreasing the electric potential of Pin ① from V_{CC}, measure the electric potential of Pin ① when Pin ⑮ output appears.
- S₁₁ : Decreasing the electric potential of Pin ⑩ from V_{CC}, measure the electric potential of Pin ⑩ when Pin ⑮ output appears.

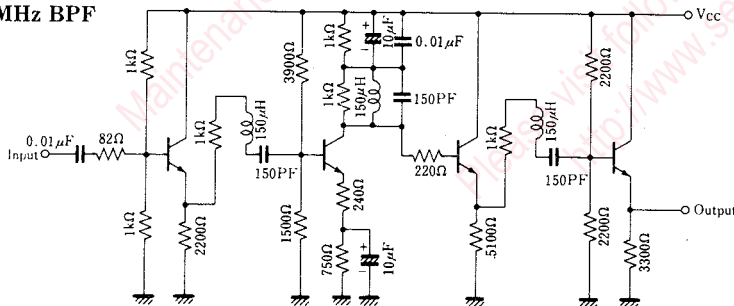
Test Circuit 3 (v_{20} , Δv_{20})



Test Circuit 4 (V_{ni3-15} , V_{ni4-15} , V_{ni8-15} , V_{ni9-15})



※1MHz BPF

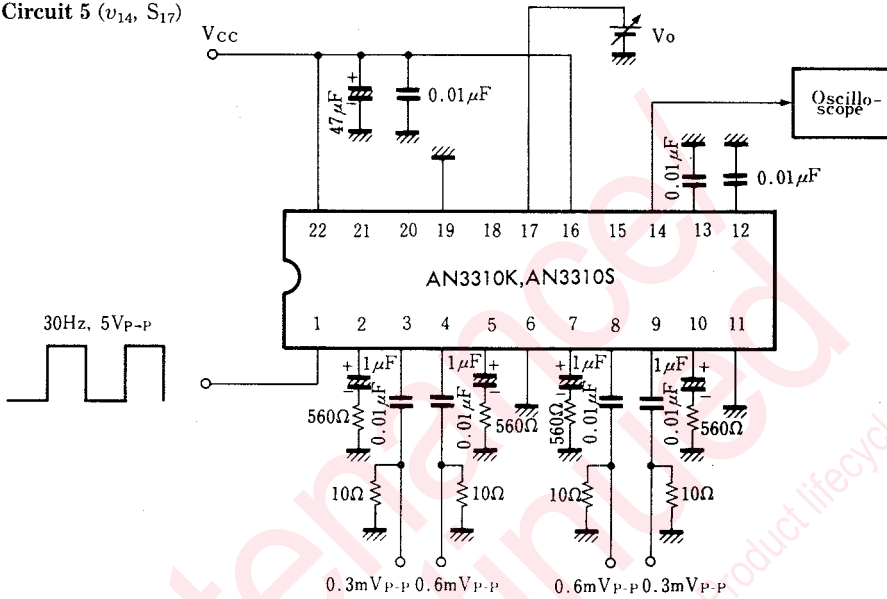


Item	Pin①	Pin②
V_{ni3-15}	V_{CC}	GND
V_{ni4-15}	GND	GND
V_{ni8-15}	V_{CC}	V_{CC}
V_{ni9-15}	GND	V_{CC}

◎ Notes for Handling

Since deterioration or destroy of characteristics may occur due to flow of overcurrent caused by the wrong insertion careful attention should be taken to handling.

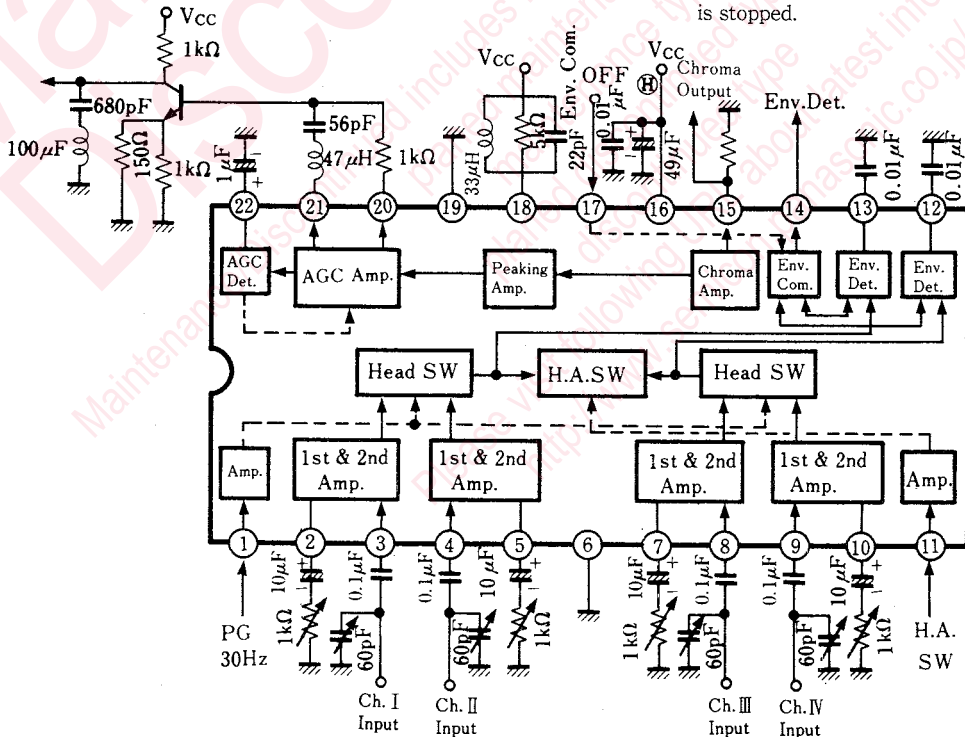
Test Circuit 5 (v_{14} , S_{17})



$V_{14} : V_o = 0V$

S_{17} : Increasing the electric potential of V_o from 0V, measure the electric potential of V_o when Pin ⑭ output is stopped.

■ Application Circuit



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